

WHAT IS CLAIMED IS:

1                   1.       A method for processing a plurality of microelectromechanical-  
2 systems (MEMS) dice, the method comprising:  
3                   securing the plurality of MEMS dice in a holder; and  
4                   performing a process step on the plurality of MEMS dice while secured in the  
5 holder.

1                   2.       The method recited in claim 1 wherein the process step is performed  
2 simultaneously on the MEMS dice while secured in the holder.

1                   3.       The method recited in claim 1 wherein the plurality of MEMS dice  
2 include unreleased MEMS dice.

1                   4.       The method recited in claim 1 wherein performing the process step  
2 comprises immersing the holder with the plurality of secured MEMS dice in a liquid.

1                   5.       The method recited in claim 4 wherein the liquid comprises a solution  
2 of hydrofluoric acid.

1                   6.       The method recited in claim 4 wherein the liquid comprises deionized  
2 water.

1                   7.       The method recited in claim 4 wherein performing the process step  
2 further comprises immersing the holder with the plurality of secured MEMS dice in a second  
3 liquid.

1                   8.       The method recited in claim 4 wherein performing the process step  
2 further comprises performing critical point drying on the plurality of MEMS dice.

1                   9.       The method recited in claim 1 wherein performing the process step  
2 comprises testing the plurality of MEMS dice.

1                   10.      The method recited in claim 1 wherein performing the process step  
2 comprises performing a step in packaging the plurality of MEMS dice

- 1 12. The method recited in claim 1 wherein the holder is made of a  
2 fluoropolymer resin.
- 1 13. The method recited in claim 12 wherein the holder is made of teflon.
- 1 14. The method recited in claim 1 further comprising preparing the  
2 plurality of MEMS dice by dicing a processed wafer.
- 1 15. An article comprising:  
2 a structural body having a plurality of stations, each such station being adapted  
3 to secure a microelectromechanical-systems (MEMS) die.
- 1 16. The article recited in claim 15 wherein each such station comprises.  
2 a recess within the structural body shaped to secure an edge of the MEMS die;  
3 and  
4 a flexible retaining arm adapted to retain the MEMS die within the recess.
- 1 17. The article recited in claim 16 wherein the flexible retaining arm  
2 includes a notch shaped for engagement with a tool for flexing the flexible retaining arm.
- 1 18. The article recited in claim 15 wherein each such station includes an  
2 access to an underside of the MEMS die.
- 1 19. The article recited in claim 18 wherein the access comprises a hole in  
2 the structural body.
- 1 20. The article recited in claim 18 wherein the access comprises a slot in  
2 the structural body.
- 1 21. The article recited in claim 15 wherein the structural body is circularly  
2 symmetric and the plurality of stations are configured symmetrically about a central axis of  
3 the structural body.
- 1 22. The article recited in claim 15 wherein the article is formed as a single  
2 fluoropolymer resin.

1 24. The article recited in claim 23 wherein the article is formed of teflon<sup>®</sup>.

1 25. An article comprising:

2 a structural body having a plurality of means for securing a  
3 microelectromechanical-systems (MEMS) die.

1 26. The article recited in claim 25 wherein each such means for securing  
2 includes flexible means for retaining the MEMS die within a recess in the structural body.

1 27. The article recited in claim 25 wherein the structural body is circularly  
2 symmetric and the plurality of means for securing are configured symmetrically about a  
3 central axis of the structural body.